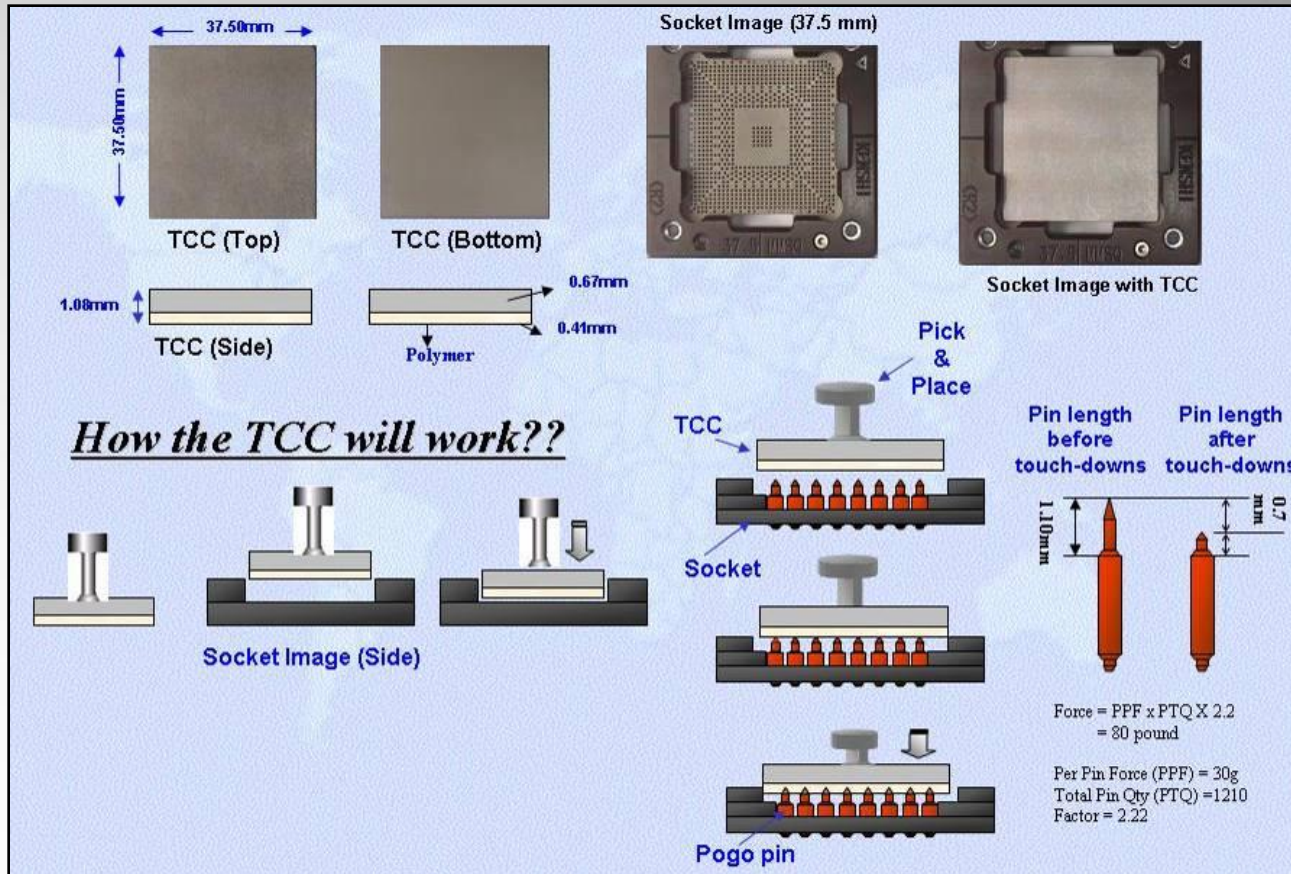


# Debris Removal at Package Test



- Polymer material applied to the “bottom side” of the package.
- Polymer material actuated into contact with the spring pins to remove and collect debris.
- Polymer material compressed against socket floor to collect loose debris.
- US and Foreign Patents pending